BALVER ZINN® | COBAR®

TECHNICAL NEWSLETTER · AUTUMN 2026

BUILT FOR RELIABILITY, FROM PASTE TO WIRE TO FLUX

Continuous miniaturisation and increasing thermal demands of the final application introduce more challenges to electronic assembly. With a balanced combination of soldering materials, the probability of field defects is dramatically reduced.

ALLOY

SN100CV®: STABILISED HIGH RELIABILITY

Increased thermal demands, especially in the automotive sector, require high reliability alloys. SN100CV® is gaining popularity and relies on increasing automotive qualifications. It offers stabilised high reliability, whilst other alloys (such as SAC based) lose significant reliability as the product ages.

By introducing atoms larger than Sn atoms, the crystalline structure of the tin matrix is disturbed, leading to a thermally more stable microstructure. Unlike other high reliability alloys, SN100CV® can be used in **all** soldering processes, including liquid processes such as wave and selective soldering.

SILVER-FREE
A high-reliability alternative to SAC305

ALL PROCESSES
Paste, cored wire, wave and selective soldering

AUTOMOTIVE
Increasing automotive qualifications

SOLDER PASTE

JEAN-151 AND AWOX®120

JEAN-151

The most versatile solder paste on the market: **10 alloys** (Pb-free, SnPb and LMP) with one and the same flux technology. Powder sizes IPC class T3 to T5 support a smooth “zero defect” printing process. Long shelf life, very long stencil life and constant printing performance, with a proven track record in intrusive reflow and other challenging applications. SN100CV® is available in JEAN-151.

AWOX®120

Reduce soldering costs without compromising reliability. AWOX®120 needs **no nitrogen** and is more highly activated for fine powders (type 4.5 to 6) and low melting alloys, helping to cut material and process costs while keeping joints reliable and of high quality.

Available in lead-free (with and without silver), lead-containing and low melting alloys.

CORED WIRE

STARCORE®234-E AND ETUX27

For robotic and manual soldering, SN100CV® and SN100C® can be combined with the latest StarCore®234-E or ETUX27 flux technology. The dedicated shape of the flux core in the StarCore® versions reduces or eliminates solder splattering. Together with excellent soldering performance, this is why StarCore®234-E is gaining explosive popularity. *Try it and you will want to buy it.*

FLUX

REGI: THE FLUX RANGE

REGI-RED

Where machine restrictions do not allow VOC free fluxes, this alcohol based ORL0 flux is the latest technology. It differs from competitors' products through performance and versatility, giving optimum soldering results even on aged OSP surfaces and leaving a minimum of very safe residues. Use with or without nitrogen.

REGI-BLUE

The latest VOC free flux technology: it eliminates VOC emissions and is the most sustainable product in the range. Thanks to its special formulation, REGI-BLUE is the only VOC free flux that shows **no corrosion** after soldering, with perfect results and the safest possible residues.

CLEANING

WHEN "NO-CLEAN" SHOULD BE CLEANED

A full range of cleaning materials is available. For localised manual cleaning, the aerosols Balver Spray Cleaner and GPC-R-114 both offer optimum cleaning performance. The Multi Cleaner covers many operations, such as stencil cleaning, whether manual, automatic or ultrasonic. For tough contamination in equipment, the Equipment Cleaner is the answer: leave the applied foam on the surface for a few minutes, then simply wipe off with a cloth. Simple and easy.

AT A GLANCE

WHICH PRODUCT FOR WHICH PROCESS

PROCESS	RECOMMENDED SOLUTION	WHY
Stencil printing and reflow	JEAN-151, AWOX®120	Long stencil life; AWOX®120 needs no nitrogen and suits fine powders
Wave and selective soldering	SN100CV® with REGI-BLUE or REGI-RED	High reliability alloy for liquid processes; REGI-BLUE is VOC free with no corrosion
Robotic and manual soldering	SN100CV® or SN100C® cored wire with StarCore®234-E or ETUX27	Reduced solder splattering, excellent soldering performance
Automotive and high thermal load	SN100CV®	Stabilised reliability that SAC alloys lose with ageing
Aged OSP surfaces	REGI-RED, REGI-GOLD	Optimum soldering performance with minimal safe residues
Post-solder cleaning	Spray Cleaner, GPC-R-114, Multi Cleaner, Equipment Cleaner	Local, stencil and equipment cleaning covered

MEET US

ELECTRONICA 2026, MUNICH

Hall A3 · Booth A3.360 · 10 to 13 November 2026

A3.360

For detailed information on the latest Balver Zinn / Cobar products, visit **www.balverzinn.com** or contact us directly. We would be happy to meet you at electronica.